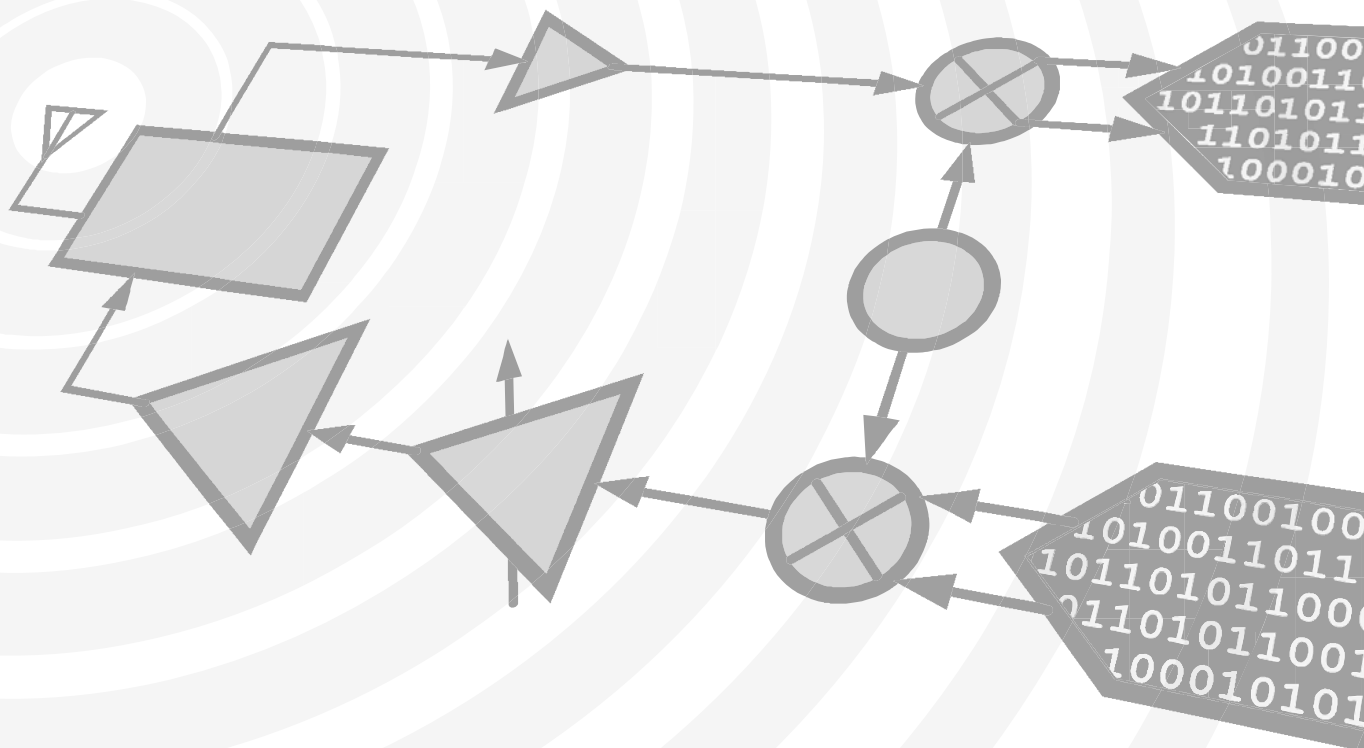




NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED



HMC493* Product Page Quick Links

Last Content Update: 08/30/2016

Comparable Parts

View a parametric search of comparable parts

Evaluation Kits

- HMC493LP3 Evaluation Board

Documentation

Data Sheet

- HMC493 Data Sheet

Reference Materials

Quality Documentation

- Package/Assembly Qualification Test Report: 16L 3x3mm QFN Package (QTR: 11003 REV: 02)
- Package/Assembly Qualification Test Report: LP2, LP2C, LP3, LP3B, LP3C, LP3D, LP3F, LP3G (QTR: 2014-0364)
- Package/Assembly Qualification Test Report: Plastic Encapsulated QFN (QTR: 05006 REV: 02)
- Semiconductor Qualification Test Report: GaAs HBT-A (QTR: 2013-00228)

Design Resources

- HMC493 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

Discussions

View all HMC493 EngineerZone Discussions

Sample and Buy

Visit the product page to see pricing options

Technical Support

Submit a technical question or find your regional support number

* This page was dynamically generated by Analog Devices, Inc. and inserted into this data sheet. Note: Dynamic changes to the content on this page does not constitute a change to the revision number of the product data sheet. This content may be frequently modified.

THIS PAGE INTENTIONALLY LEFT BLANK

HMC493LP3 / 493LP3E

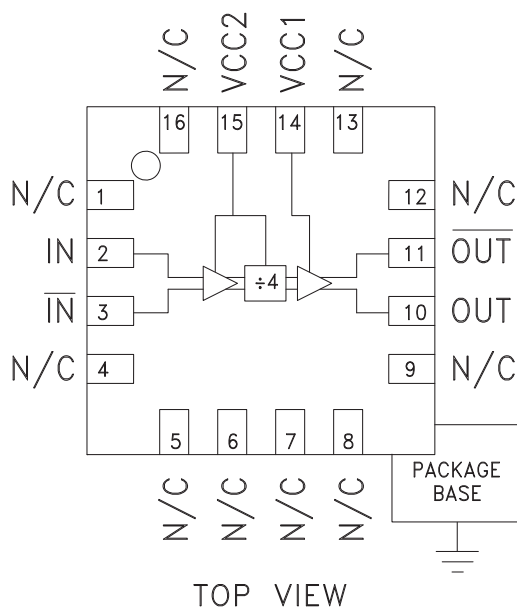
SMT GaAs HBT MMIC
DIVIDE-BY-4, DC - 18 GHz

Typical Applications

Prescaler for DC to 18 GHz PLL Applications:

- Point-to-Point / Multi-Point Radios
- VSAT Radios
- Fiber Optic
- Test Equipment
- Military

Functional Diagram



Features

- Ultra Low SSB Phase Noise: -150 dBc/Hz
- Very Wide Bandwidth
- Output Power: -4 dBm
- Single DC Supply: +5V
- 3x3 mm QFN SMT Package

General Description

The HMC493LP3 & HMC493LP3E are low noise Divide-by-4 Static Dividers utilizing InGaP GaAs HBT technology packaged in leadless 3x3 mm QFN surface mount plastic packages. This device operates from DC (with a square wave input) to 18 GHz input frequency from a single +5V DC supply. The low additive SSB phase noise of -150 dBc/Hz at 100 kHz offset helps the user maintain excellent system noise performance.

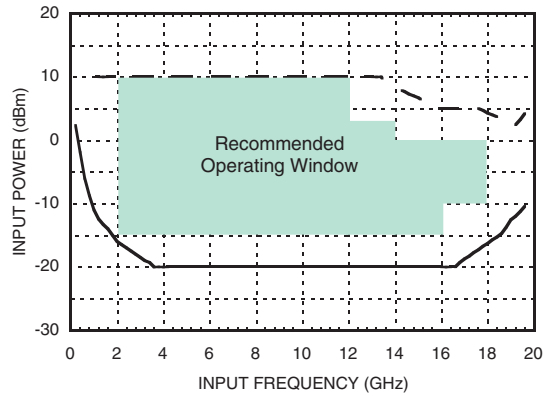
Electrical Specifications, $T_A = +25^\circ \text{C}$, 50 Ohm System, $V_{CC} = +5V$

Parameter	Conditions	Min.	Typ.	Max.	Units
Maximum Input Frequency		18	18.5		GHz
Minimum Input Frequency	Sine Wave Input. [1]		0.2	0.5	GHz
Input Power Range	$F_{in} = 2$ to 12 GHz	-20	-15	+10	dBm
	$F_{in} = 12$ to 14 GHz	-20	-15	+3	dBm
	$F_{in} = 14$ to 16 GHz	-20	-15	0	dBm
	$F_{in} = 16$ to 18 GHz	-15	-10	0	dBm
Output Power	$F_{in} = 0.5$ to 18 GHz	-7	-4		dBm
Reverse Leakage	Both RF Outputs Terminated		55		dB
SSB Phase Noise (100 kHz offset)	$P_{in} = 0$ dBm, $F_{in} = 6$ GHz		-150		dBc/Hz
Output Transition Time	$P_{in} = 0$ dBm, $F_{out} = 882$ MHz		100		pSec
Supply Current ($I_{CC1} + I_{CC2}$)			96		mA

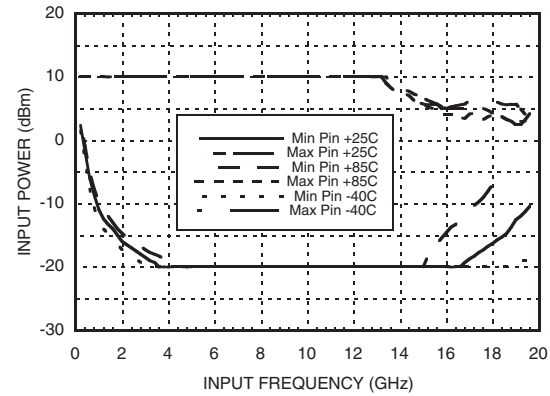
1. Divider will operate down to DC for square-wave input signal

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
 20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
 Order On-line at www.hittite.com

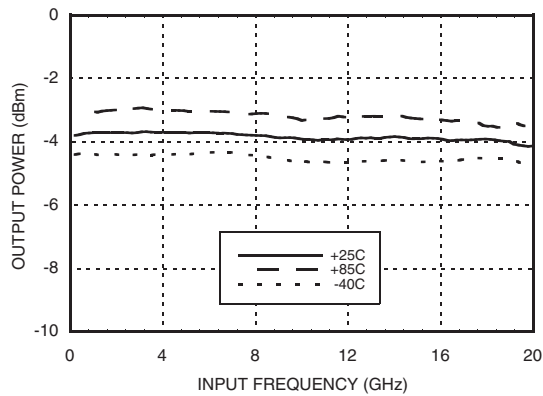
Input Sensitivity Window, $T = 25^\circ\text{C}$



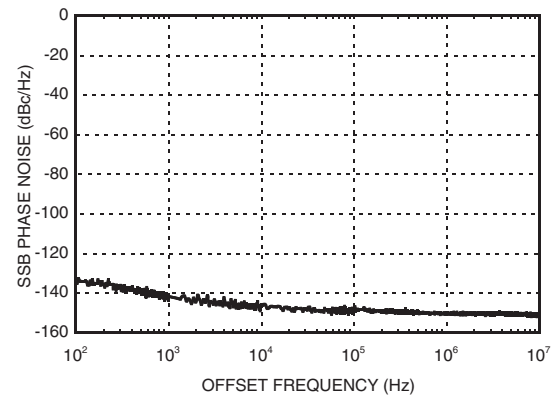
Input Sensitivity Window vs. Temperature



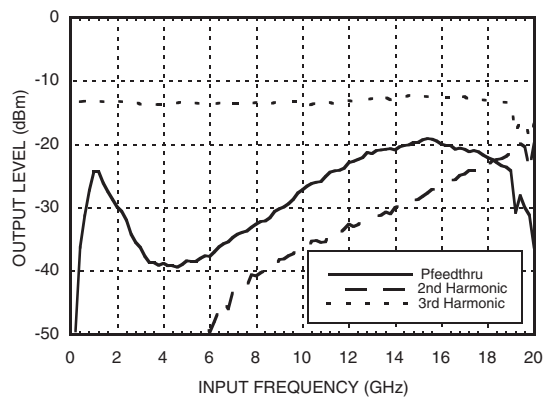
Output Power vs. Temperature



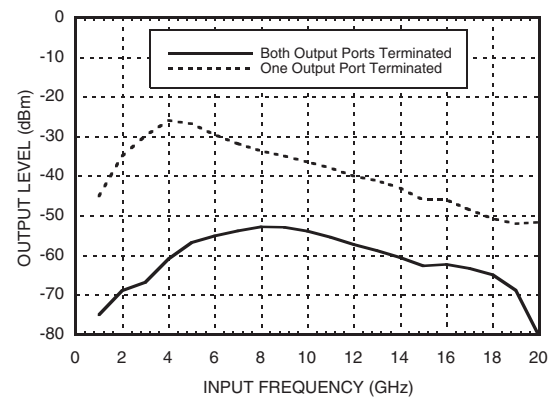
SSB Phase Noise Performance, $P_{in} = 0\text{ dBm}$, $T = 25^\circ\text{C}$



Output Harmonic Content, $P_{in} = 0\text{ dBm}$, $T = 25^\circ\text{C}$



Reverse Leakage, $P_{in} = 0\text{ dBm}$, $T = 25^\circ\text{C}$





MICROWAVE CORPORATION

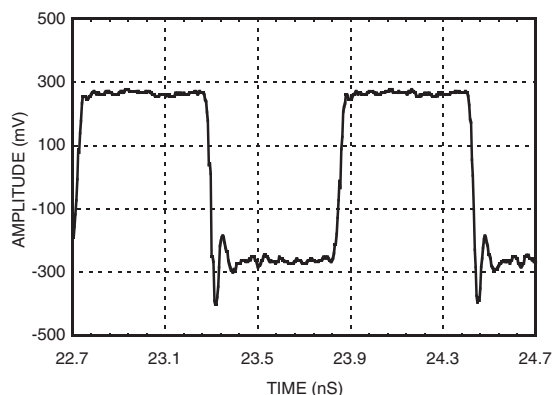
v04.0507



HMC493LP3 / 493LP3E

SMT GaAs HBT MMIC
DIVIDE-BY-4, DC - 18 GHz

Output Voltage Waveform,
Pin= 0 dBm, Fout= 882 MHz, T= 25 °C



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

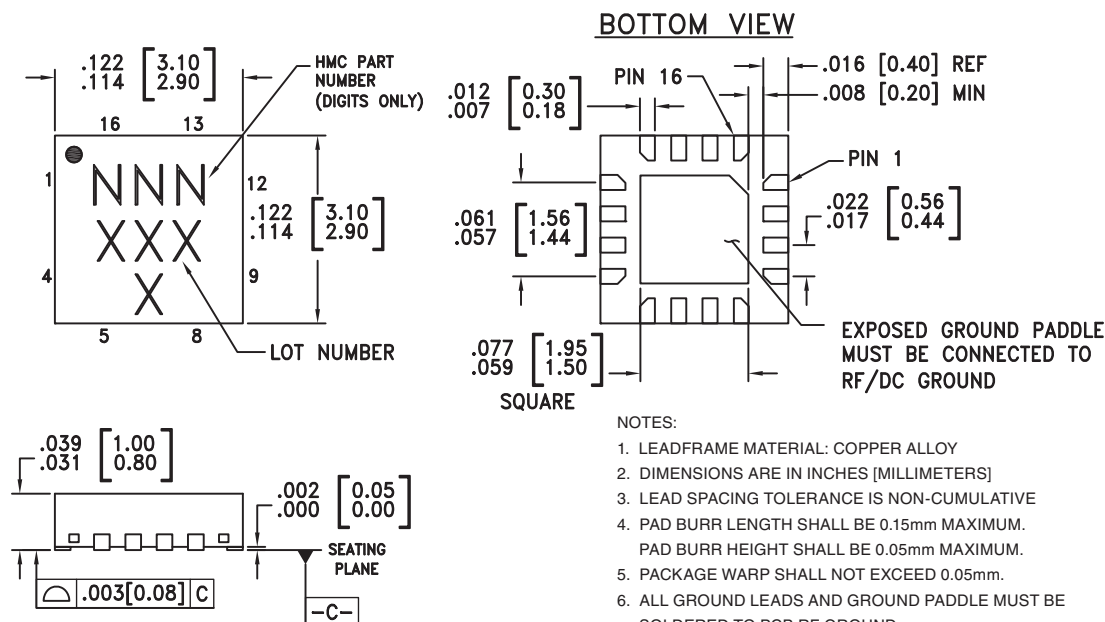
Absolute Maximum Ratings

RF Input (Vcc = +5V)	+13 dBm
Supply Voltage (Vcc1, Vcc2)	+5.5V
Channel Temperature (Tc)	135 °C
Continuous P _{diss} (T = 85 °C) (derate 11.9 mW/°C above 85 °C)	593 mW
Thermal Resistance (R _{TH}) (junction to ground paddle)	84 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

Typical Supply Current vs. Vcc

Vcc1, Vcc2 (V)	Icc (mA)
4.75	84
5.0	96
5.25	108

Note: Divider will operate over full voltage range shown above

Outline Drawing**Package Information**

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC493LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	493 XXXX
HMC493LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	493 XXXX

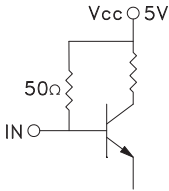
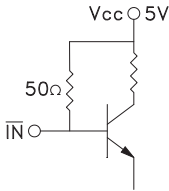
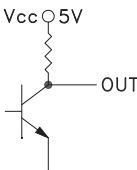
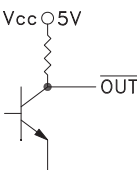
[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
 20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
 Order On-line at www.hittite.com

Pin Description

Pin Number	Function	Description	Interface Schematic
1, 4-9, 12, 13, 16	N/C	No connection.	
2	IN	RF Input must be DC blocked.	
3	$\overline{\text{IN}}$	RF Input 180° out of phase with pin 2 for differential operation. AC ground for single ended operation.	
10	OUT	Divided Output.	
11	$\overline{\text{OUT}}$	Divided output 180° out of phase with pin 10.	
14, 15	Vcc1, Vcc2	Supply voltage 5V ± 0.25V. Connect both pins to +5V supply.	
	GND	Ground: Backside of package has exposed metal ground slug which must be connected to RF/DC ground.	

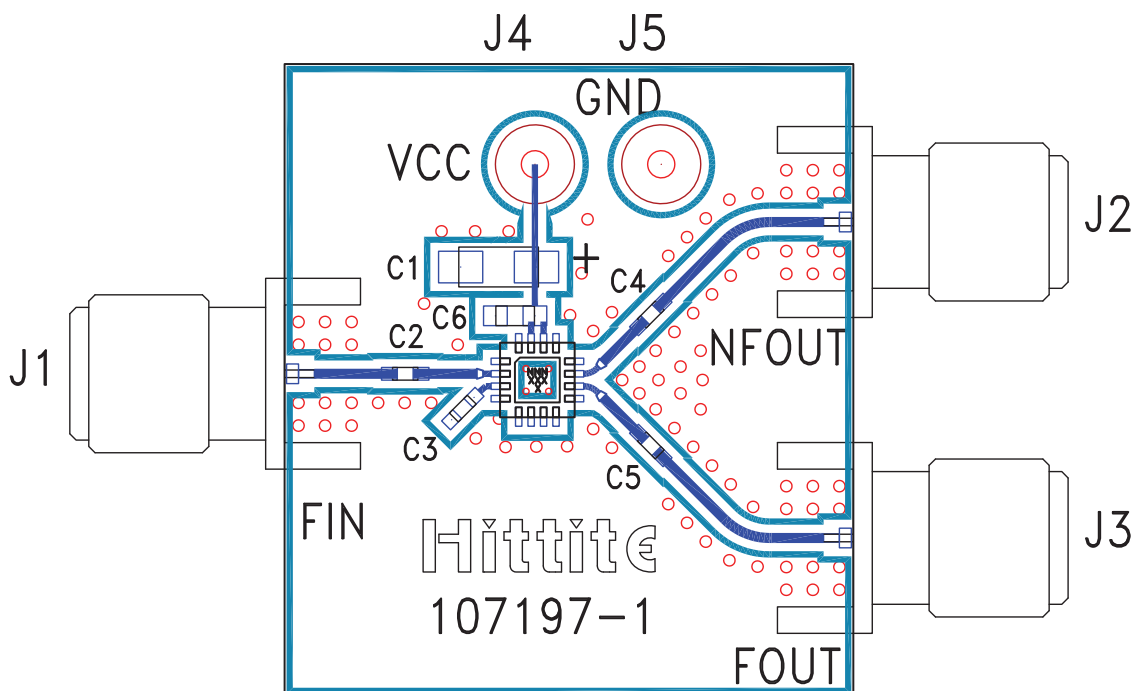


MICROWAVE CORPORATION

v04.0507

**HMC493LP3 / 493LP3E**

SMT GaAs HBT MMIC
DIVIDE-BY-4, DC - 18 GHz

Evaluation PCB**List of Materials for Evaluation PCB 107384 ^[1]**

Item	Description
J1 - J3	PCB Mount SMA RF Connector
J4, J5	DC Pin
C2 - C5	100 pF Capacitor, 0402 Pkg.
C6	1000 pF Capacitor, 0603 Pkg.
C1	2.2 uF Tantalum Capacitor
U1	HMC493LP3 / HMC493LP3E Divide-by-2
PCB [2]	107197 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request. This evaluation board is designed for single ended input testing. J2 and J3 provide differential output signals.

Application Circuit

